

AMENDMENTS TO THE CLAIMS

1-24. (Cancelled)

25. (Currently amended) A heat-treating method for a packaging product, comprising:
providing a packaging product formed by enclosing a content material within a packaging material comprising at least a layer of hydrophilic gas-barrier resin selected from the group consisting of ethylene-vinyl alcohol copolymer, polyamide (co-)polymers and glycolic acid (co-)polymer, and
heat-treating the packaging product with hot water,
wherein the hot water is caused to contain a water-soluble compound
comprising an inorganic electrolyte.

26. (Currently amended) ~~A~~The heat-treating method according to Claim 25, wherein the hot water has a temperature of 60-100°C to effect a boiling heat-treatment.

27. (Currently amended) ~~A~~The heat-treating method according to Claim 25, wherein the hot water has a temperature exceeding 100°C to effect a retort heat-treatment.

28. (Currently amended) ~~A~~The heat-treating method according to Claim 25, wherein the hot water contains the water-soluble compound at a concentration exceeding 0.1 wt.%.

29. (Currently amended) ~~A~~The heat-treating method according to Claim 25, wherein the hot water contains the water-soluble compound at a concentration of at least 1 wt.%.

30. (Cancelled)

31. (Currently amended) ~~A~~The heat-treating method according to Claim ~~30~~25, wherein the water-soluble compound is a water-soluble inorganic salt.

32. (Currently amended) ~~A-The~~ heat-treating method according to Claim 31, wherein the water-soluble compound is a chloride selected from the group consisting of sodium chloride, magnesium chloride, and potassium chloride.

33. (Currently amended) ~~A-The~~ heat-treating method according to Claim 32, wherein the water-soluble compound is sodium chloride.

34. (Currently amended) ~~A-The~~ heat-treating method according to Claim 25, wherein the water-soluble compound is a water-soluble organic compound.

35. (Currently amended) ~~A-The~~ heat-treating method according to Claim 34, wherein the water-soluble compound is a water-soluble alcohol.

36-38. (Cancelled)

39. (Currently amended) ~~A-The~~ heat-treating method according to Claim 25, wherein the packaging material has a multi-layer structure.

40. (Currently amended) ~~A-The~~ heat-treating method according to Claim 39, wherein the hydrophilic gas-barrier resin layer is disposed as a surface layer contacting the hot water of the packaging material.

41. (Currently amended) ~~A-The~~ heat-treating method according to Claim 39, wherein the hydrophilic gas-barrier resin layer is disposed as an inner layer not directly contacting the hot water of the packaging material.

42. (Currently amended) ~~A-The~~ heat-treating method according to Claim 41, wherein the gas-barrier resin is glycolic acid (co-)polymer.

43. (Withdrawn) A packaged product, which has been heat-treated by a heat-treating method according to Claim 25.

44. (Withdrawn) A packaged product according to Claim 43, wherein the heat-treated packaging material has a haze below 20%.
45. (Withdrawn) A heat-treated packaged product, comprising a heat-treated packaging material having a multi-layer structure including an inner layer of a hydrophilic gas-barrier resin layer selected from the group consisting of ethylene-vinyl alcohol copolymer and glycolic acid (co-)polymer, and a content material enclosed within the packaging material, wherein the heat-treated packaging material has a haze below 20%.
46. (Withdrawn) A packaged product according to Claim 45, wherein the hydrophilic gas-barrier resin is ethylene-vinyl alcohol copolymer.
47. (Withdrawn) A packaged product according to Claim 45, wherein the hydrophilic gas-barrier resin is glycolic acid (co-)polymer.
48. (Withdrawn) A packaged product according to Claim 43, wherein the packaged material has been subjected to a heat-shrinking treatment during the heat treatment.